

Material Declaration Report

Package Type:	TQFN 48L (7x7mm)
Pericom Package Code:	ZB48(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	125.9998
Termination Plating:	Matte Sn
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	2011/12/15

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	75.6000	Greatek	Epoxy Resin	Trade secret	8.000	6.0480
			Phenol Resin	Trade secret	6.000	4.5360
			Carbon Black	1333-86-4	0.500	0.3780
			Silica fused	60676-86-0	75.000	56.7000
			Silica fused	7631-86-9	10.000	7.5600
			Silica crystalline	14808-60-7	0.500	0.3780
LEADFRAME	40.3200		Copper	7440-50-8	97.021	39.1188
			Iron	7439-89-6	2.350	0.9475
			Silver	7440-22-4	0.453	0.1828
			Zinc	7440-66-6	0.111	0.0447
			Phosphorus	7723-14-0	0.065	0.0262
SILICON DIE	6.0730		Silicon (Si)	7440-21-3	99.192	6.0239
			Non-hazardous Metal	Proprietary	0.808	0.0491
DIE ATTACH EPOXY	0.1008		Silver	7440-22-4	80.000	0.0806
			Epoxy Resin	Proprietary	17.000	0.0171
			Non-hazardous Metal	Proprietary	3.000	0.0030
GOLD WIRE	0.1260		Gold(Au)	7440-57-5	99.990	0.1260
			Impurities	-	0.010	0.0000
SOLDER PLATING	3.7800		Tin (Sn)	7440-31-5	99.990	3.7796
			Impurity	-	0.010	0.0004

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
		<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE														
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm														
O	O	O	O	O	O														
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																			